PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's	Revisio	Datum:	Seite:
PRINTED CIRCUIT BOARDS	01	4.11.2001	1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
06	180	FR4	55	L36.70	P11	

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_180_FR4_55_L36.70_p11

Layers	in µ	Material	Build-Up	Assembly
Layer-1	55µ	Copper		B
	115µ	Prepreg	(115 µ PrePreg-Type: 2116)	
	115µ	Prepreg		
Layer-2	70µ	Copper		A1
	360µ	L-FR4		
Layer-3	70µ	Copper		
	115µ	Prepreg		
	115µ	Prepreg		
Layer-4	70µ	Copper		A2
	360µ	L-FR4		
Layer-5	70µ	Copper		
	115µ	Prepreg		
	115µ	Prepreg		
Layer-99	55µ	Copper		

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PCB
Printed Circuit Boards GmbH
Oberdiessemer Strasse 15,
47805 Krefeld - Germany

Fon: ++49 (0) 21 51 825 1
Fax: ++49 (0) 21 51 932 450
Web: http://www.p-c-b.de
eMail: info@p-c-b.de

Reg.-No.: KR HRB 2863
VAT-ID-No.: DE 120 157 078
Management:
Manfred Völker

Deutsche Bank Krefeld
BIC-(SWIFT)-Code: DEUTDEDD320
IBAN: DE18 3207 0080 0064 0318 00
IID: 320 700 80, BAN: 064 0318

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